

## Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard  
<http://www.ipc.org/IPC-175x>

Form Type\*  
Distribute

**Declaration Class\***  
**Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information**

### Supplier Information

<b>Company Name *</b> Fairchild Semiconductor	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	<b>Response Date*</b> Sat, May 26, 2012 05:17 AM
<b>Contact Name *</b> David Lancaster	Title - Contact Product Ecology	<b>Phone - Contact *</b> 801-562-7455	<b>Email - Contact *</b> david.lancaster@fairchildsemi.com
<b>Authorized Representative *</b> David Lancaster	Title - Representative Product Ecology	<b>Phone - Representative *</b> 801-562-7455	Email - Representative * david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
SB560	SB560	DO-201AD			SUBCONTRACTOR	1.173	g	Each

### Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Matte Tin (Sn)	Other	Not Applicable	C	seconds	Not Applicable

\* Required Field

<b>RoHS Material Composition Declaration</b>	<b>Declaration Type * Custom</b>
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<b>RoHS Directive 2002/95/EC</b>	<b>RoHS Definition:</b> Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium
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Providing for limitations below, we certify that the Fairchild Semiconductor product(s) list in this document are compliant to directive 2002/95/EC of the European Parliament and of the council on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS directive). Specifically, this product(s) does not contain the substances in the RoHS definition above in concentrations greater than the maximum limit value(a).

Fairchild has implemented procedures to ensure our products and the materials in our products conform to regulatory requirements worldwide. Fairchild Semiconductor certifies that the information provided in this document is correct as of the date indicated on this document. However, not all materials in Fairchild's products may have been independently verified or tested with regard to substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

(a) Maximum limit does not apply to applications for which exemptions have been granted by the RoHS directive. Fairchild product may utilize exemption 5 and 7a.

<b>RoHS Declaration *</b>	<b>4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions</b>	<b>Supplier Acceptance * Accepted</b>
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**Exemptions:** If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2006/690/EC

7a. Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85 % by weight or more lead).

**Declaration Signature**

Supplier Signature	 DAVID LANCASTER - PRODUCT ECOLOGY MANAGER
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**Homogeneous Material Composition Declaration for Electronic Products**

Item/SubItem Name DO-201AD

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
CSS Wire	Other Ferrous alloys, non-stainless steels	529.000	Supplier		Carbon	2.650	7440-44-0	2260
			Supplier		Copper	185.000	7440-50-8	157746
			Supplier		Iron	340.000	7439-89-6	289911
			Supplier		Manganese	1.060	7439-96-5	904
			Supplier		Phosphorus	0.265	7723-14-0	226
			Supplier		Sulfur	0.265	7704-34-9	226
Chip	Other inorganic materials	0.093	Supplier		Silicon	0.093	7440-21-3	79
Die Attach	Other Nonferrous metals & alloys	0.112	A	Lead/Lead Compounds	Lead	0.104	7439-92-1	89
			Supplier		Silver	0.003	7440-22-4	2
			Supplier		Tin	0.006	7440-31-5	5
Dumet Wire	Other Ferrous alloys, non-stainless steels	360.000	Supplier		Cobalt	1.800	7440-48-4	1535
			Supplier		Iron	203.000	7439-89-6	173094
			Supplier		Manganese	2.880	7439-96-5	2456
			B	Nickel (external applications only)	Nickel	151.000	7440-02-0	128755
			Supplier		Silicon	1.080	7440-21-3	921
Encapsulation	Thermoplastics	272.167	B	Antimony/Antimony Compounds	Antimony Trioxide	5.712	1309-64-4	4871
			B	Brominated Flame Retardants (other than PBCs or PBDEs)	Bromine Resin	4.900	6386-73-8	4178
			Supplier		Epoxy Resin	68.000	29690-82-2	57982
			Supplier		Silica, vitreous	193.555	60676-86-0	165041
Plating	Other Nonferrous metals & alloys	11.400	Supplier		Tin	11.400	7440-31-5	9721